



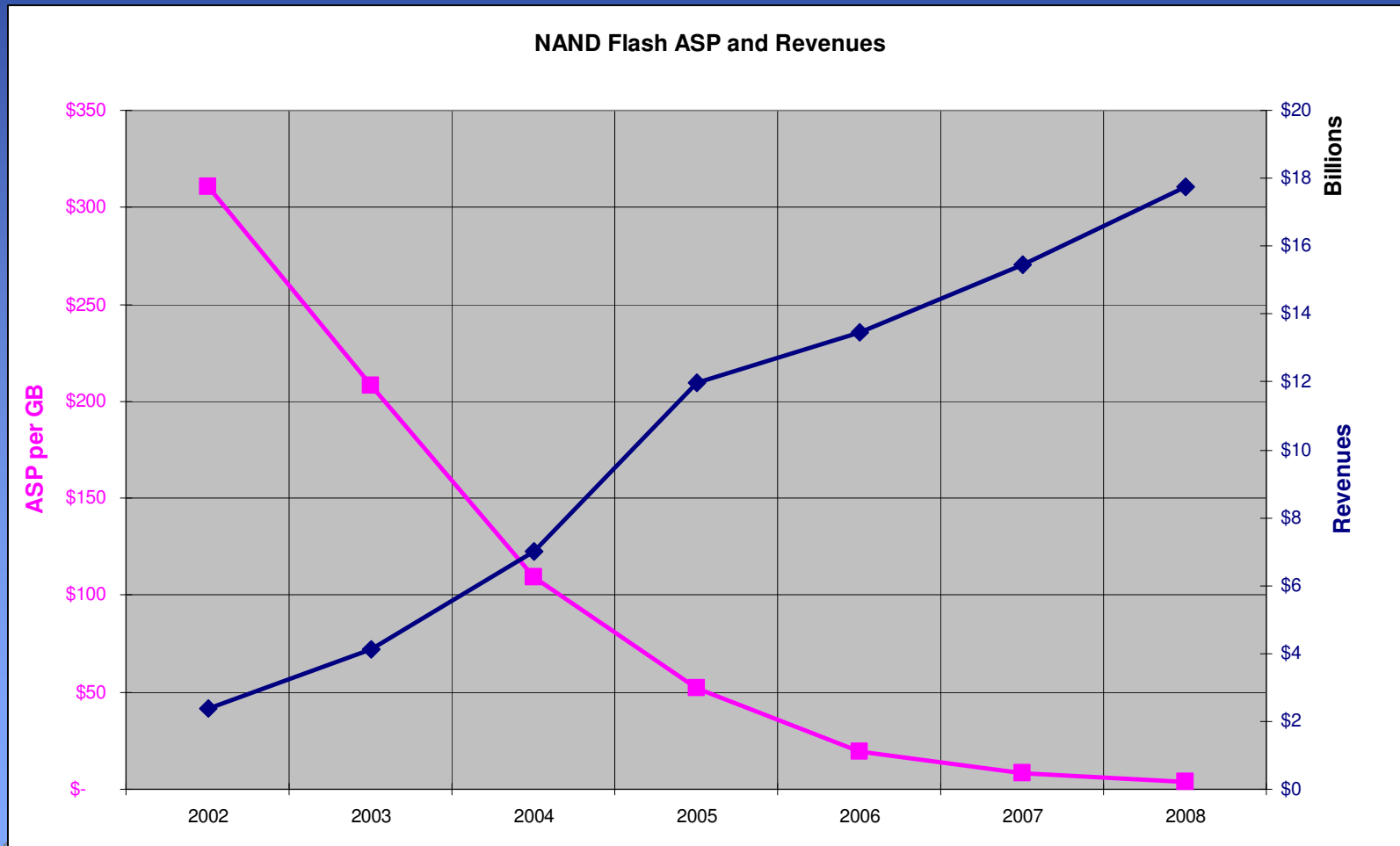
3D: Beyond Conventional Flash and into the Future

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Santa Clara, CA USA
August 2008

Alper Ilkbahar, SanDisk 3D

NAND Flash Industry Growth



Santa Clara, CA USA
August 2008

Source: Gartner

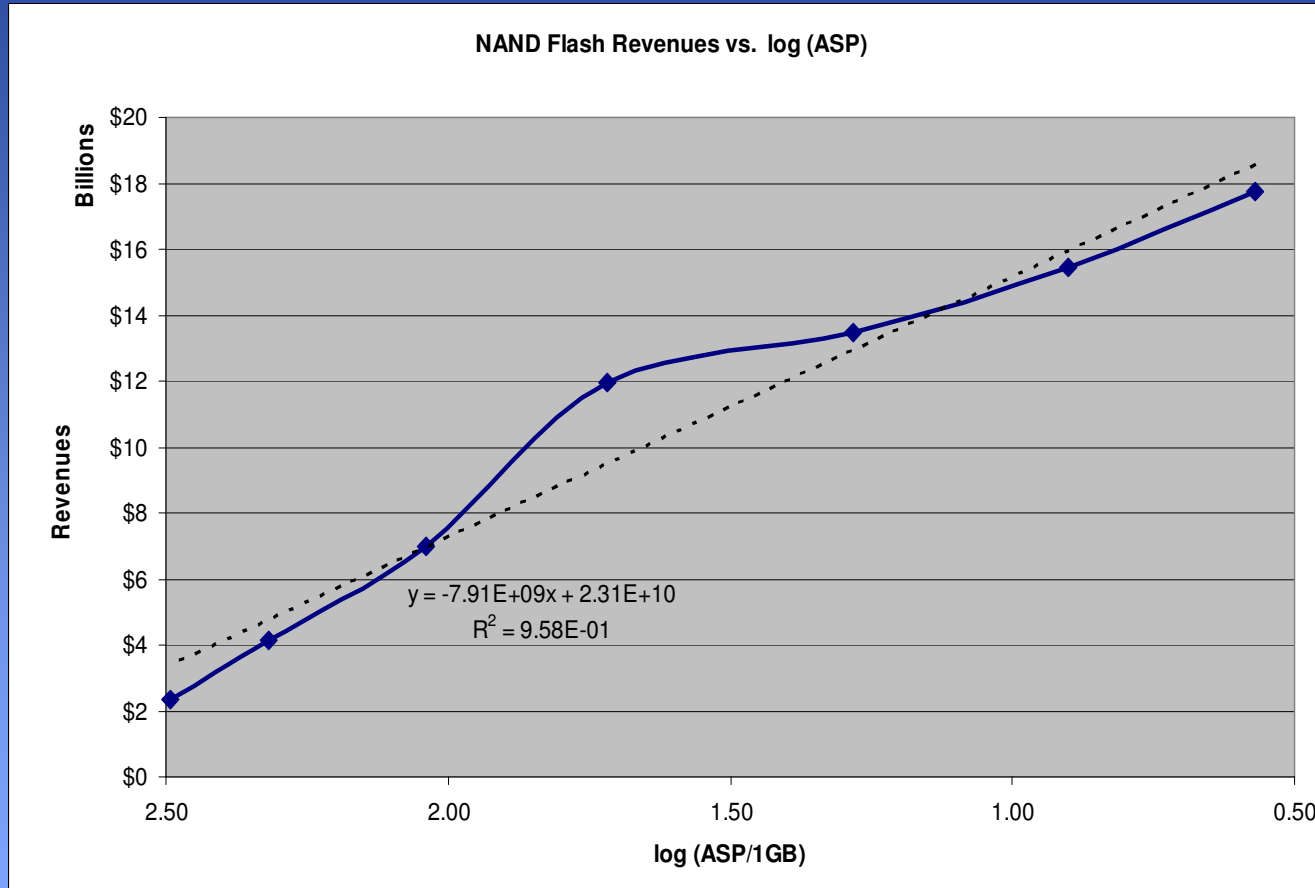
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What drives cost-per-bit?

- Multiple bit per cell (MLC) technologies
- Economies of scale
- But beyond everything SCALING

Flash Revenues vs. ASP

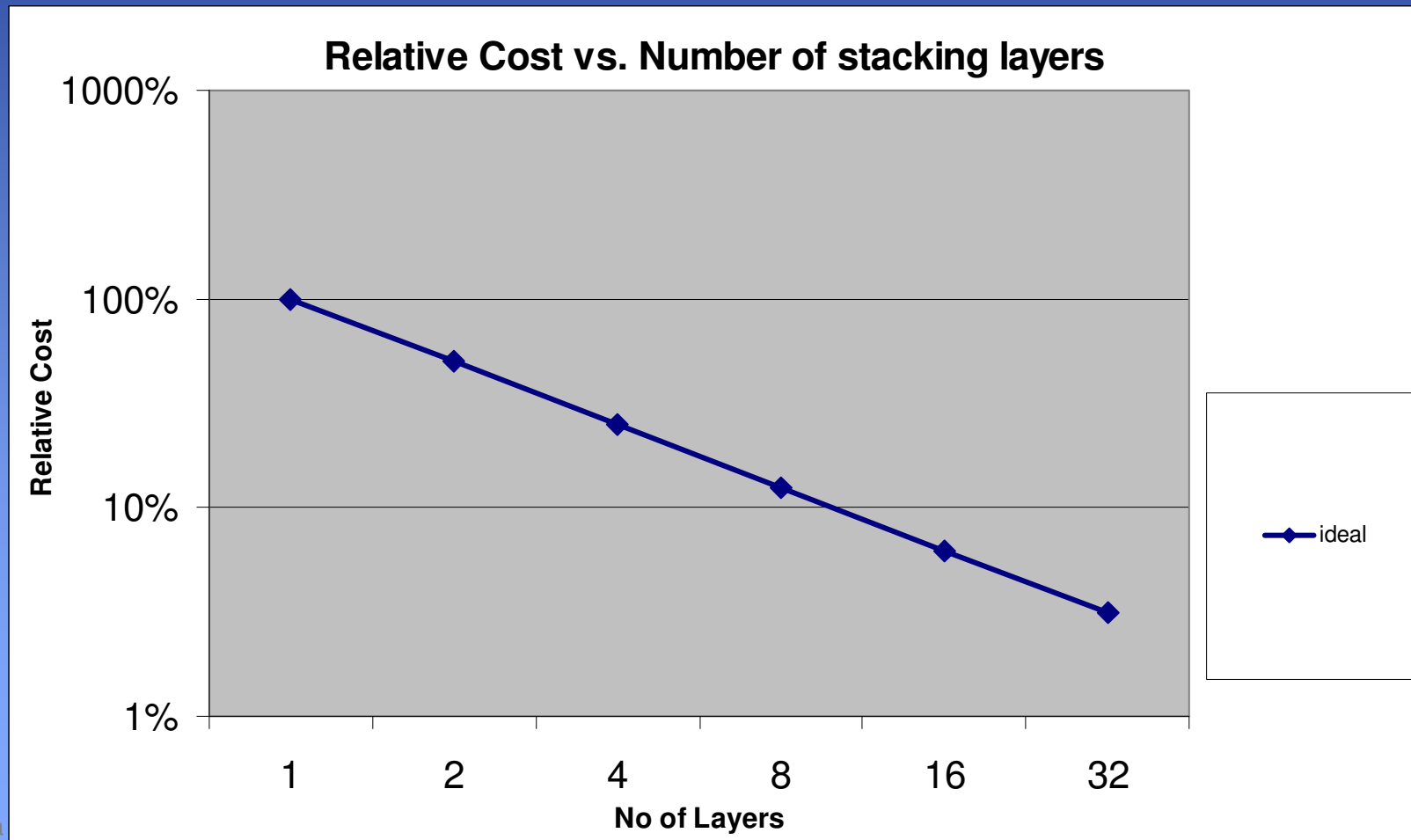


$$\text{Rev} = \$23\text{B} - 7.9 \times \log (\text{ASP}/\text{GB})$$

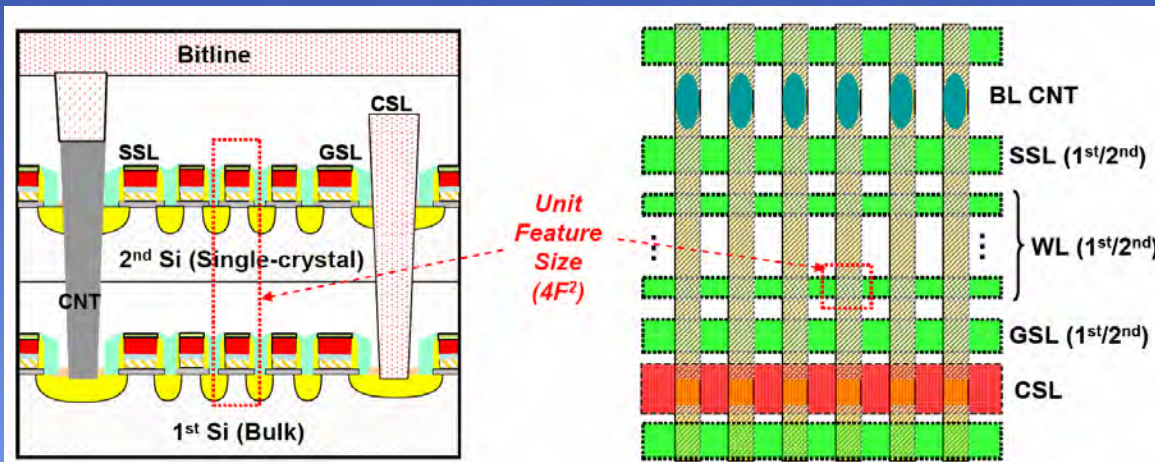
- “If we build it (at the right price), they will buy it”
- Exponential ASP reduction needed to drive industry growth
- We need to continue scaling



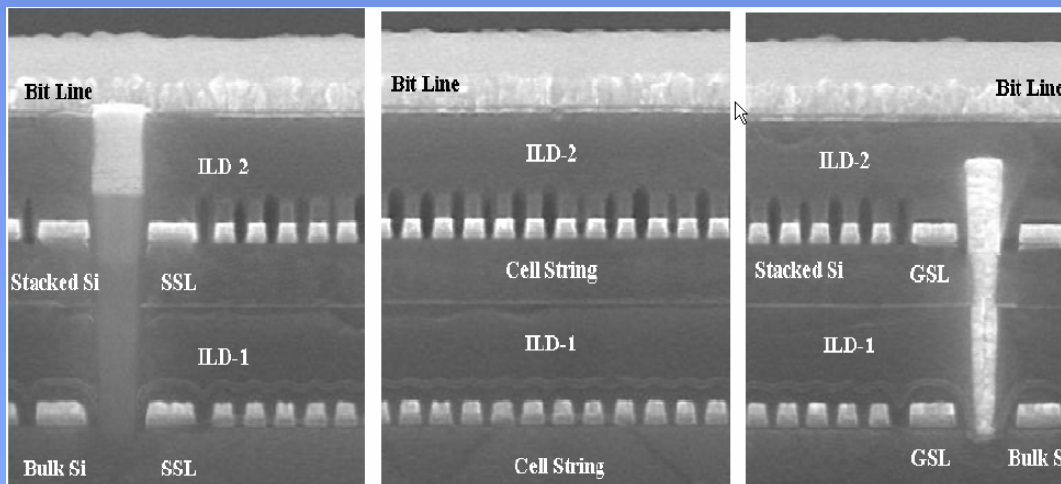
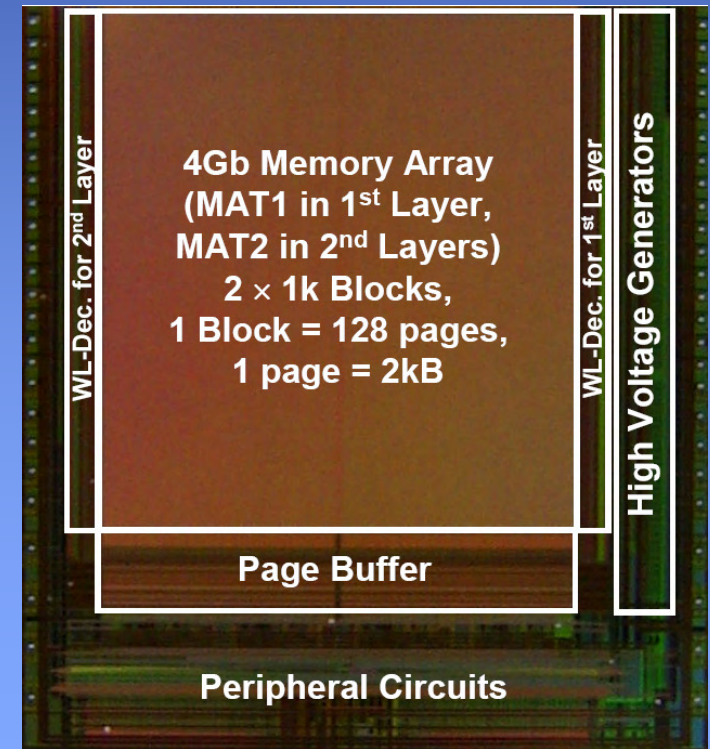
Can stacking layers of memory solve our scaling problem?



Examples of stacked memories: 3D NAND

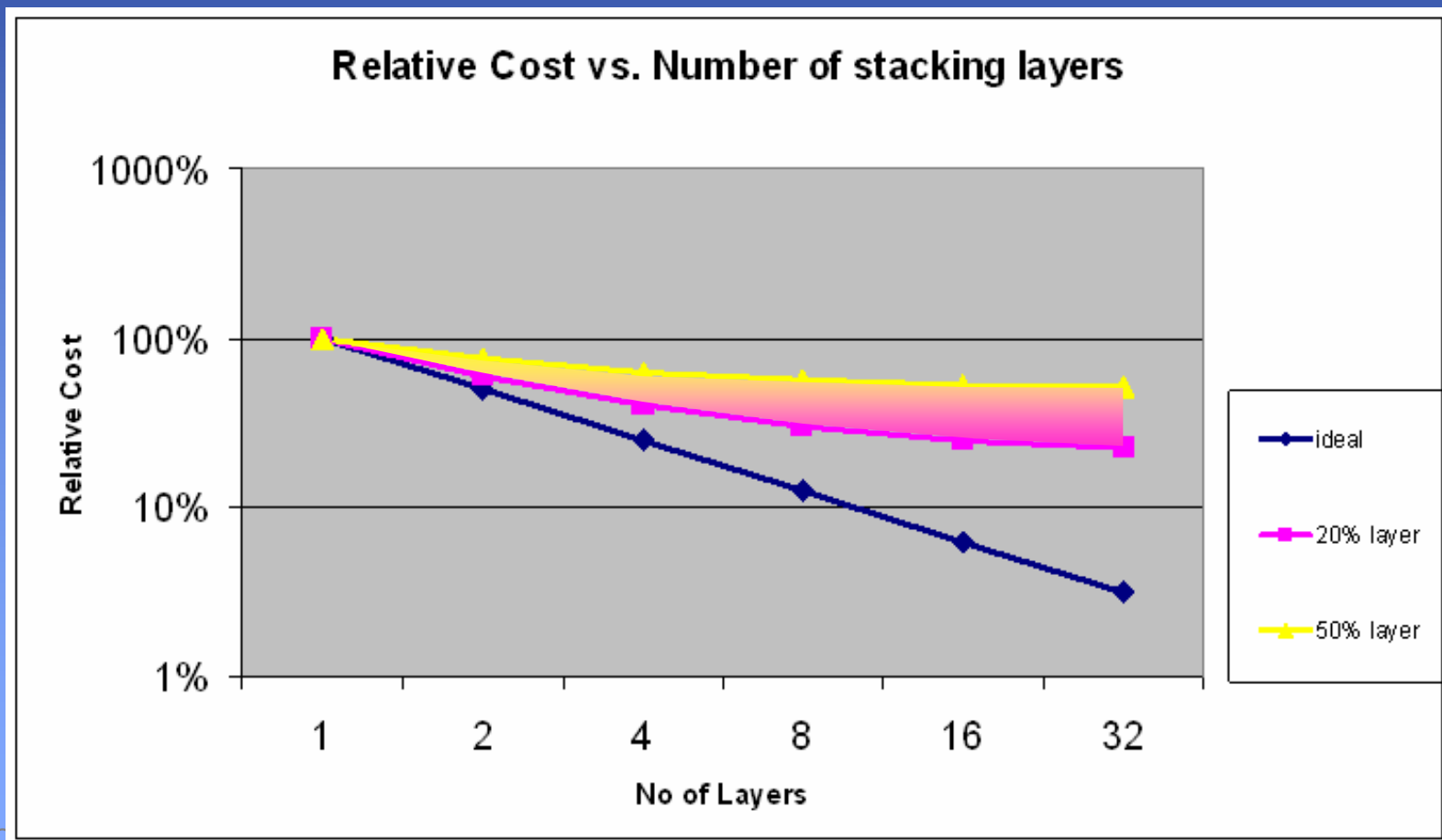


Samsung, IEDM '06, ISSCC '08



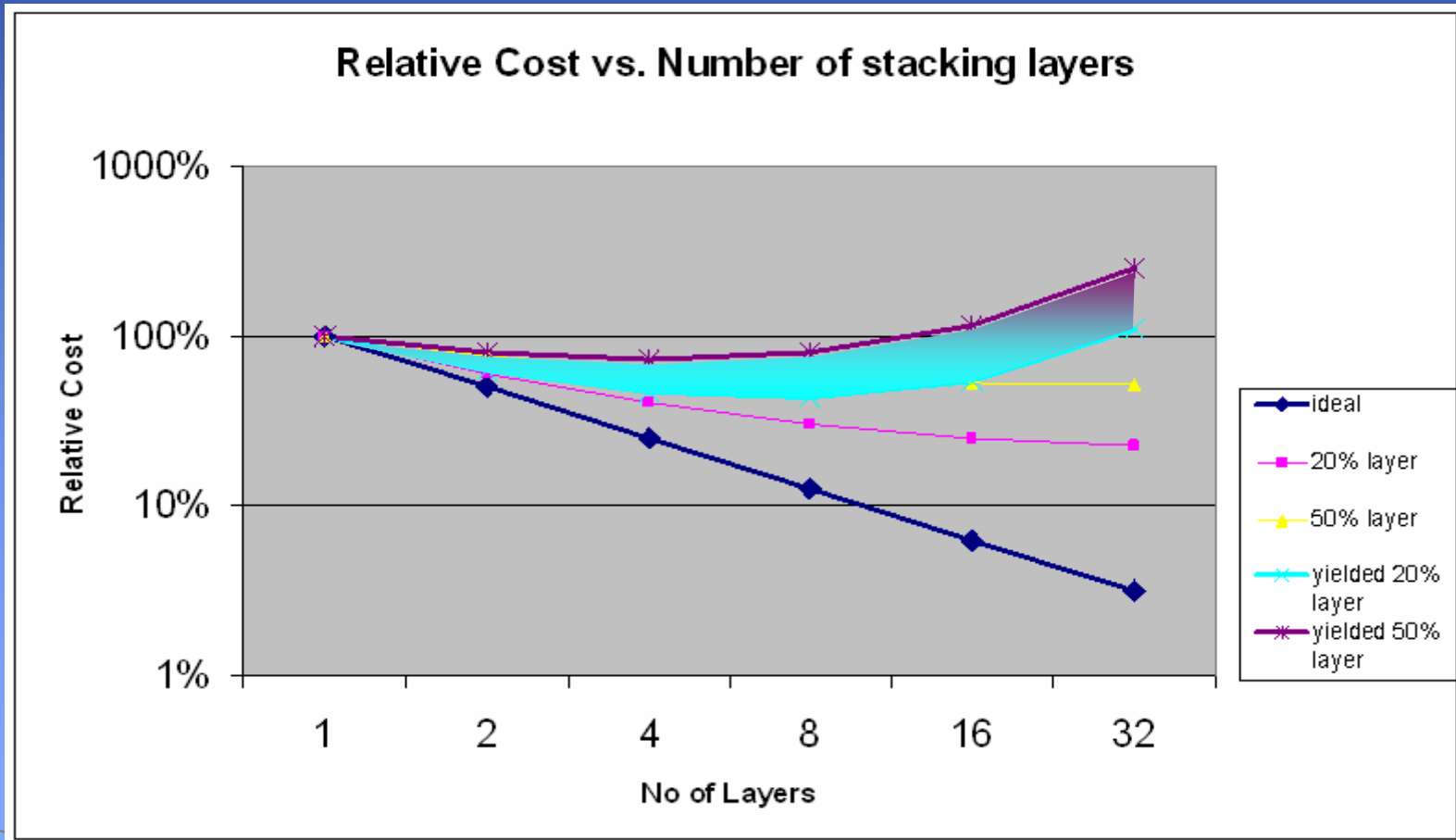
Additional Layers are not free

- Die size overhead and additional process steps increase cost



...and yield of each layer is <100%

- Stacking may provide one-time cost benefits, but it alone is not a replacement for scaling



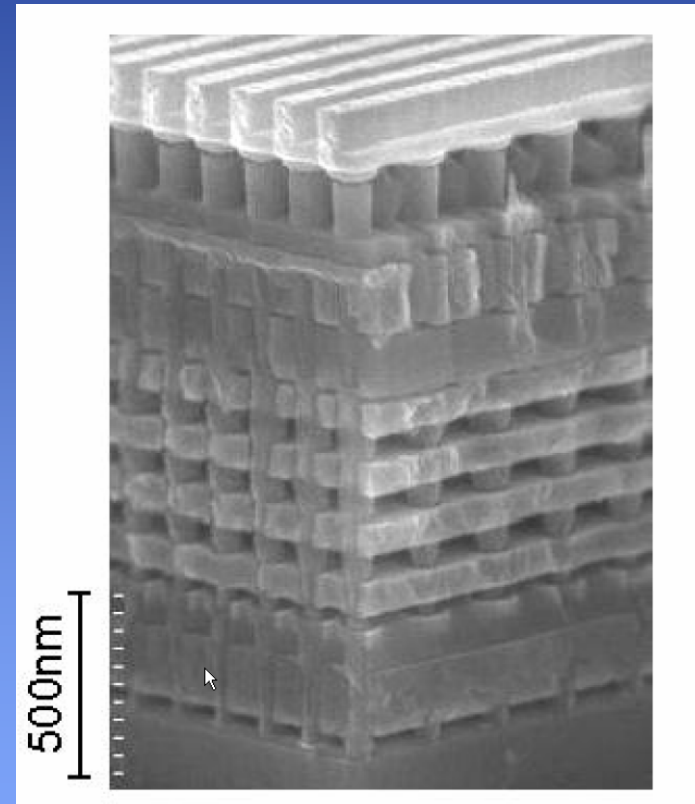
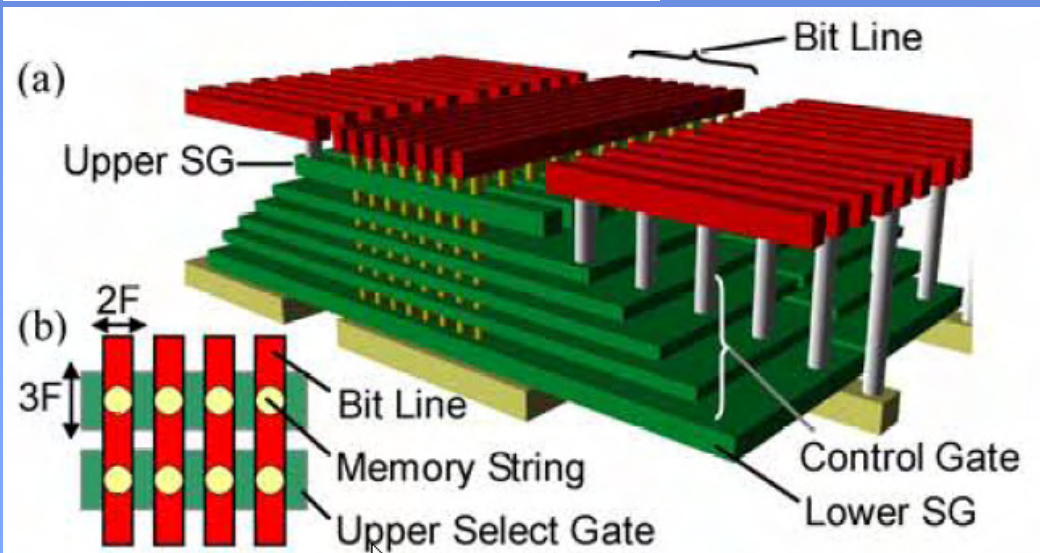
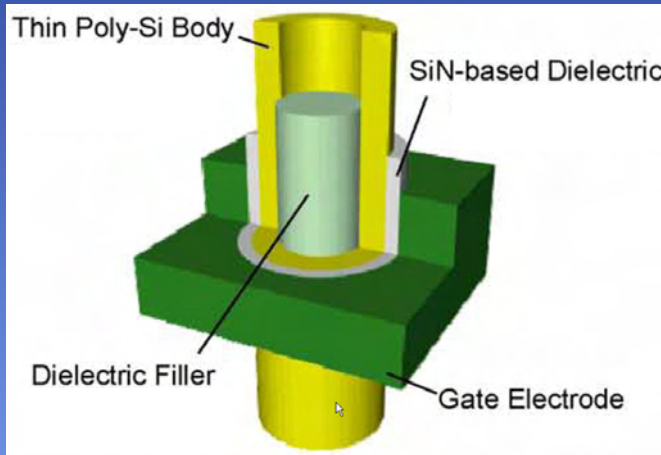


3D: Vertical Devices

- Another perspective of 3D:

Can we build memory devices in the vertical dimension that are easier to scale?

Example of Vertical Devices in a 3D stack: Bit-Cost Scalable Flash



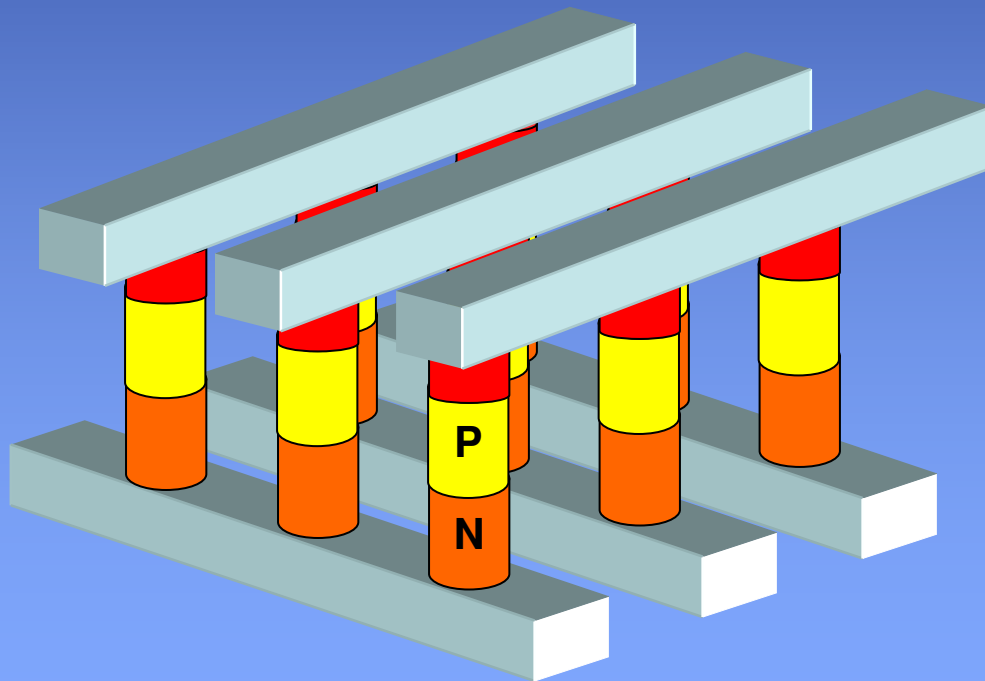
Toshiba, IEDM '07



Ultimate 3D Memory - Scalable and Stackable Cross-Point Diode Array

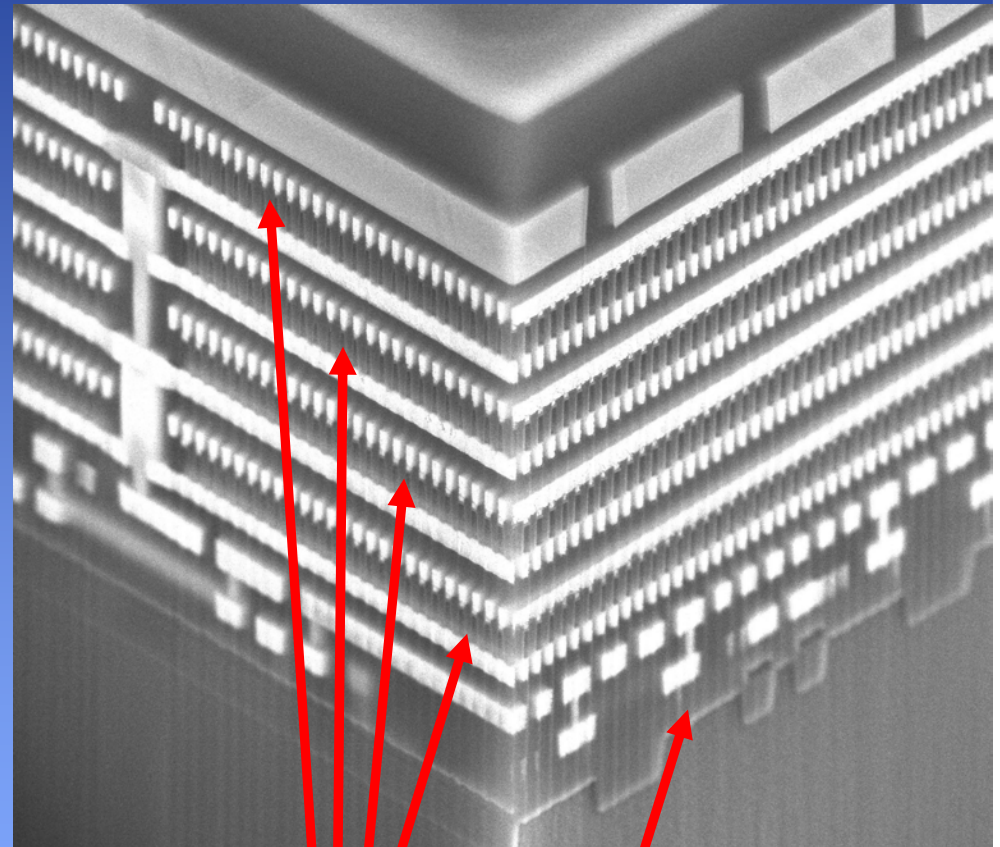
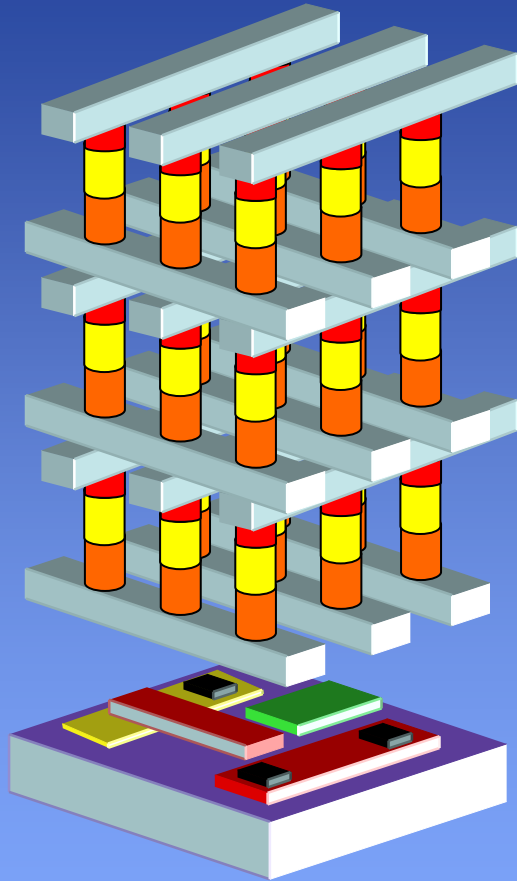
Resistance Change Materials

Chalcogenides (PCM)
Metal Oxides
Solid Electrolytes
Magnetic materials
and others...





Ultimate 3D Memory - Scalable and Stackable Cross-Point Diode Array



4 Layers of Memory

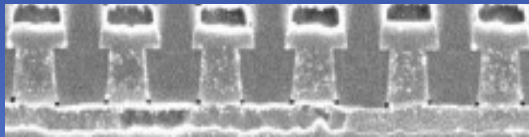
Periphery Circuits

Santa Clara, CA USA
August 2008

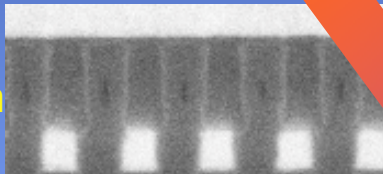
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Five Generations of 3D Diode Arrays

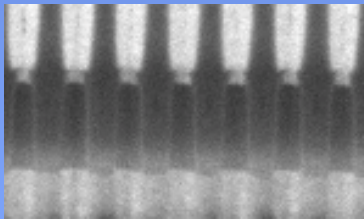
250nm



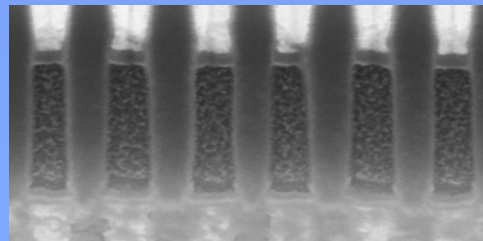
130nm



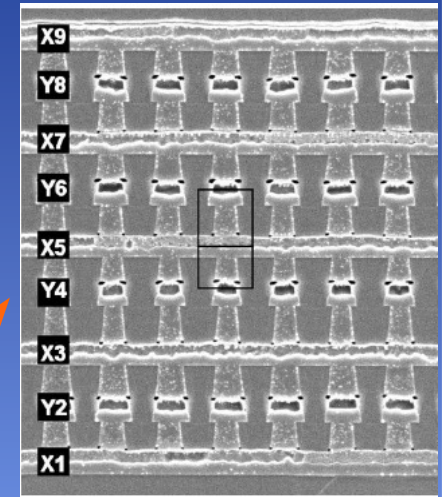
80nm



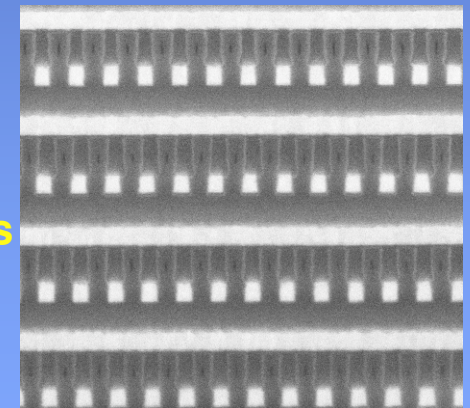
45nm



8-Layers



4-Layers



1-Layer

**SCALABLE
&
STACKABLE**



Bold Predictions

- NAND Flash will continue scaling beyond current predictions through not only process and device but also system-level innovation
- Investment in alternative technologies that do not have a long-term scaling path will have limited returns
- 3D diode arrays with the right switching material will replace Flash